



Volume 12, Issue 3



From the Director's Desk

James Amano, Senior Director

New 3D Packaging & Integration Committee

Furthering the advance of new, innovative semiconductor packaging technologies. [Read More](#)

Survey on Fan-Out Panel Level Packaging Standardization

Help guide the direction of Standards activity. [Read More](#)

New Electron Microscopy Workflow TF Formed

Keeping up with demand for Electron Microscopy in semiconductor manufacturing. [Read More](#)

Awards at SEMICON West

SEMI honored four industry leaders for their outstanding accomplishments in developing Standards for the electronics and related industries. [Read More](#)

SEMI E175-1116: Specification for Subsystem Energy Saving Mode Communication (SESMC)

Saving energy and cutting costs. [Read More](#)

SEMI A1: Specification for Horizontal Communication Between Equipment for Factory Automation System

Equipment communication protocol for flow shop style manufacturing. [Read More](#)

PCB ECI SNARF

New activity to define equipment communication interface for PCB manufacturing. [Read More](#)

S8 Ergonomics Revision

Significant updates to critical ergonomics standard. [Read More](#)

New Display Standard: Test Method of Color Reproduction and Perceptual Contrast

Advanced image quality evaluation method. [Read More](#)

Standards Calendar

November 6-9

[North America Standards Fall 2017 Meetings](#)

November 14-15

[Standards Meetings at SEMICON Europa 2017](#)

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